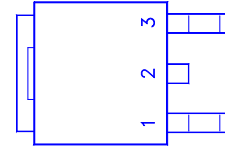
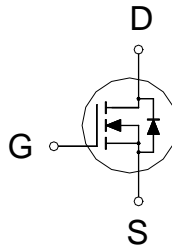




**PRODUCT SUMMARY**

$V_{(BR)DSS}$	$R_{DS(ON)}$	$I_D$
150V	55m $\Omega$	24.6A



- 1. GATE
- 2. DRAIN
- 3. SOURCE

**ABSOLUTE MAXIMUM RATINGS ( $T_A = 25\text{ }^\circ\text{C}$  Unless Otherwise Noted)**

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Drain-Source Voltage		$V_{DS}$	150	V
Gate-Source Voltage		$V_{GS}$	$\pm 20$	V
Continuous Drain Current	$T_C = 25\text{ }^\circ\text{C}$	$I_D$	24.6	A
	$T_C = 100\text{ }^\circ\text{C}$		15.5	
Pulsed Drain Current <sup>1</sup>		$I_{DM}$	60	
Avalanche Current		$I_{AS}$	11.6	
Avalanche Energy	$L = 1\text{mH}$	$E_{AS}$	67.9	mJ
Power Dissipation	$T_C = 25\text{ }^\circ\text{C}$	$P_D$	83	W
	$T_C = 100\text{ }^\circ\text{C}$		33	
Junction & Storage Temperature Range		$T_J, T_{stg}$	-55 to 150	$^\circ\text{C}$

**THERMAL RESISTANCE RATINGS**

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Case	$R_{\theta JC}$		1.5	$^\circ\text{C} / \text{W}$
Junction-to-Ambient	$R_{\theta JA}$		62.5	

<sup>1</sup>Pulse width limited by maximum junction temperature.

**ELECTRICAL CHARACTERISTICS ( $T_J = 25\text{ }^\circ\text{C}$ , Unless Otherwise Noted)**

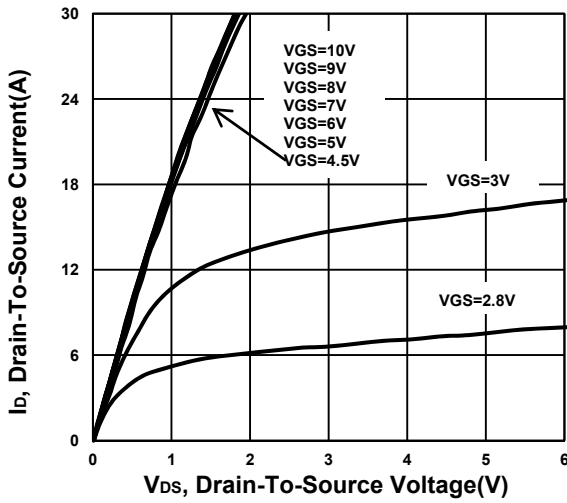
PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
<b>STATIC</b>						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$	150			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	1.3	1.9	2.3	
Gate-Body Leakage	$I_{GSS}$	$V_{DS} = 0\text{V}, V_{GS} = \pm 20\text{V}$			$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 120\text{V}, V_{GS} = 0\text{V}$			1	$\mu\text{A}$
		$V_{DS} = 100\text{V}, V_{GS} = 0\text{V}, T_J = 125\text{ }^\circ\text{C}$			10	

Drain-Source On-State Resistance <sup>1</sup>	$R_{DS(ON)}$	$V_{GS} = 4.5V, I_D = 10A$	43	65	mΩ
		$V_{GS} = 10V, I_D = 15A$	42	55	
Forward Transconductance <sup>1</sup>	$g_{fs}$	$V_{DS} = 5V, I_D = 10A$	76		S
<b>DYNAMIC</b>					
Input Capacitance	$C_{iss}$	$V_{GS} = 0V, V_{DS} = 25V, f = 1MHz$	2049		pF
Output Capacitance	$C_{oss}$		184		
Reverse Transfer Capacitance	$C_{rss}$		81		
Gate Resistance	$R_g$	$V_{GS} = 0V, V_{DS} = 0V, f = 1MHz$	1		Ω
Total Gate Charge <sup>2</sup>	$Q_g$	$V_{GS} = 10V, V_{DS} = 75V, I_D = 15A$	41		nC
Gate-Source Charge <sup>2</sup>	$Q_{gs}$		6.4		
Gate-Drain Charge <sup>2</sup>	$Q_{gd}$		10.9		
Turn-On Delay Time <sup>2</sup>	$t_{d(on)}$	$V_{DS} = 75V, I_D \cong 15A, V_{GS} = 10V, R_{GEN} = 6\Omega$	17		nS
Rise Time <sup>2</sup>	$t_r$		18		
Turn-Off Delay Time <sup>2</sup>	$t_{d(off)}$		68		
Fall Time <sup>2</sup>	$t_f$		45		
<b>SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (<math>T_J = 25^\circ C</math>)</b>					
Continuous Current	$I_S$			24.6	A
Forward Voltage <sup>1</sup>	$V_{SD}$	$I_F = 15A, V_{GS} = 0V$		1	V
Reverse Recovery Time	$t_{rr}$	$I_F = 15A, di_F/dt = 100A / \mu S$	60		nS
Reverse Recovery Charge	$Q_{rr}$		118		nC

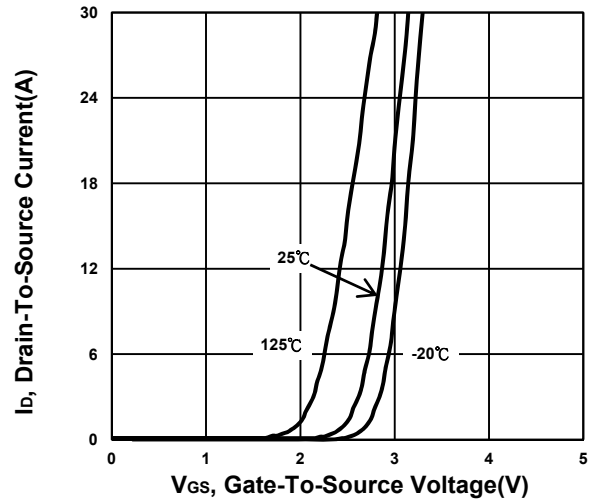
<sup>1</sup>Pulse test : Pulse Width ≤ 300 μsec, Duty Cycle ≤ 2%.

<sup>2</sup>Independent of operating temperature.

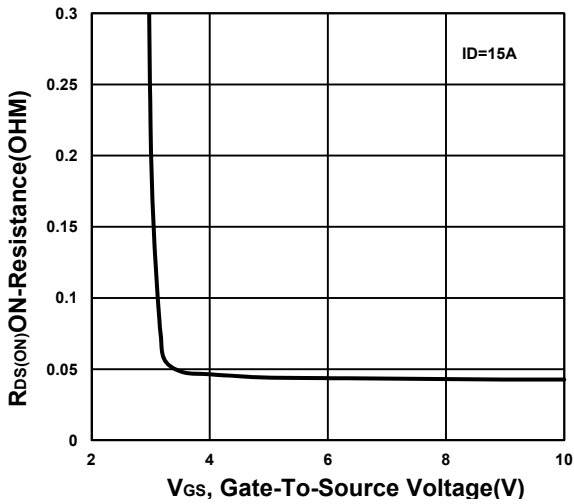
**Output Characteristics**



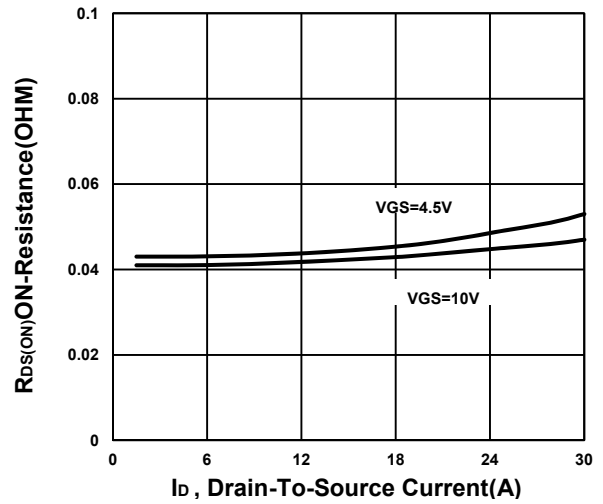
**Transfer Characteristics**



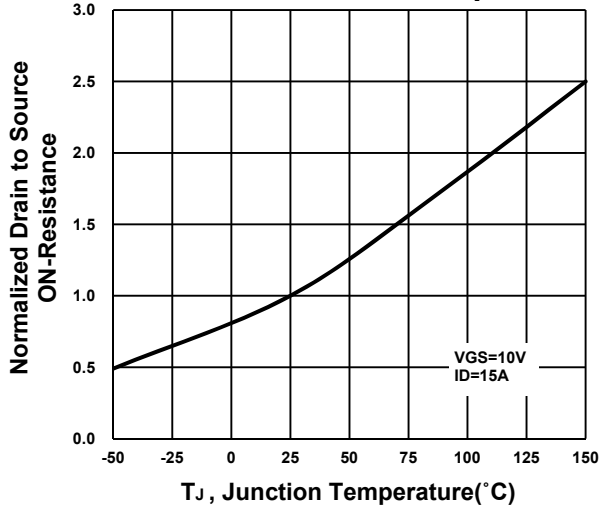
**On-Resistance VS Gate-To-Source**



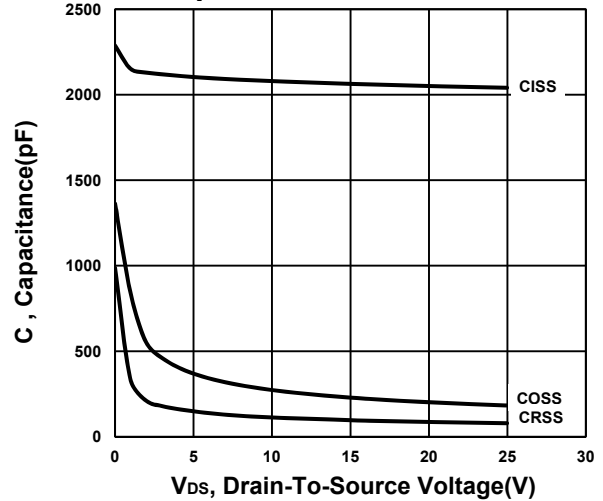
**On-Resistance VS Drain Current**



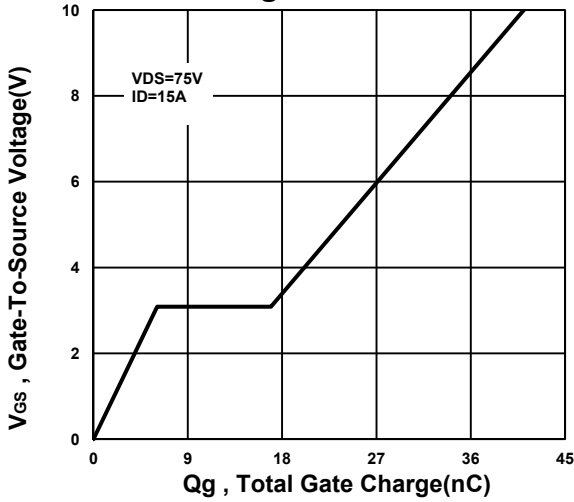
**On-Resistance VS Temperature**



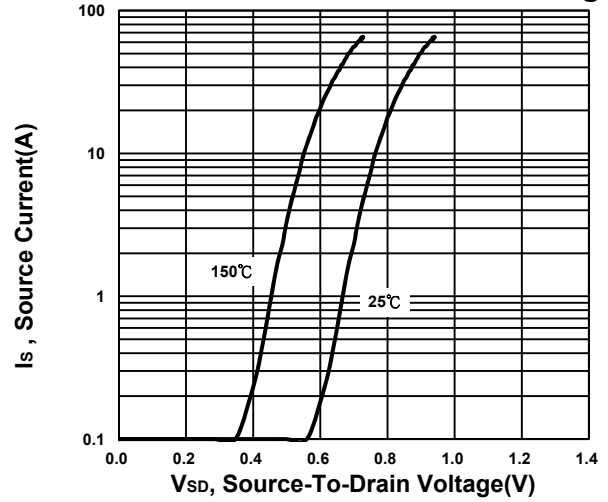
**Capacitance Characteristic**



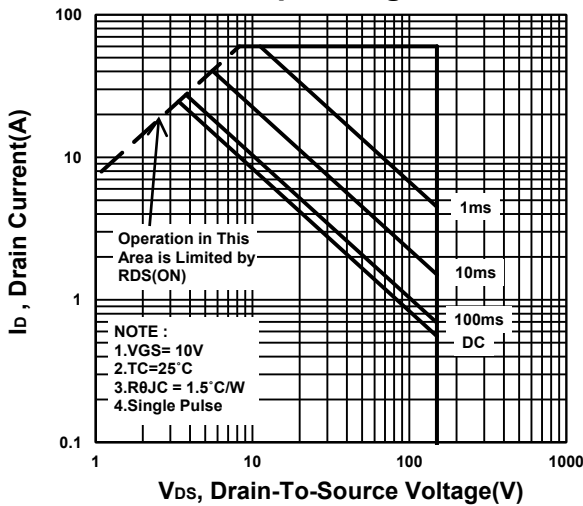
**Gate charge Characteristics**



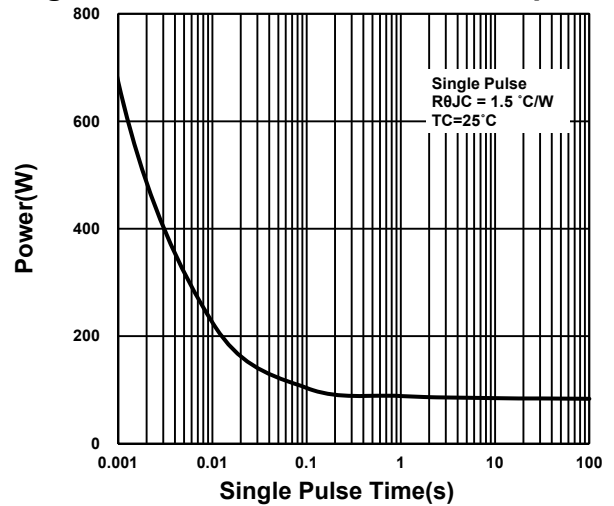
**Source-Drain Diode Forward Voltage**



**Safe Operating Area**



**Single Pulse Maximum Power Dissipation**



**Transient Thermal Response Curve**

